Product Specification

CUSTOMER：	
DESCRIPTION：	RF TRANSMISSION LINE TRANSFORMER
MNC P/N：	RFT-134SG
REVISION：	X2
CUSTOMER P/N：	
ISSUED DATE：	2017-01-16
PHOTO OF PRODUCT：	
WEIGHT：	0.06g

PREPARED BY	CHECKED BY	APPROVED BY
Wen Lee	Sonny Zhang	Simon Zhang

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CHANGE RECORD

REV.	DESCRIPTION (Content or Reason For Change)	DATE	REVISER
X0	INITIAL RELEASE	2017-01-11	Wen Lee
X1	According to customer's request,Updated the specification: Changed product height from 3.2mm Max to 3.0mm Max.	2017-01-13	Wen Lee
X2	According to customer's request,Updated the specification: Changed product width from 3.81mm to 4.06mm; Changed product Base from 3+3 Pin to 3+2 Pin.	2017-01-16	Wen Lee

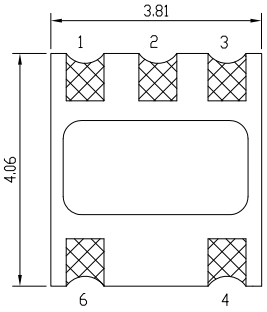
RF TRANSMISSION LINE TRANSFORMER

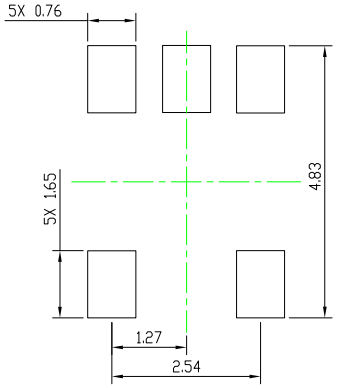
- RF Transmission Line Transformer
- Impedance=50Ω
- Operating temperature range: -40℃ to +85℃
- Storage temperature range: -55℃ to +100℃
- RoHS compliant

Electrical Specifications @25°C,Z_0=50Ω									
Part Number	Ω Ratio	Insertion Loss (Max)			Amplitude Unbalance(Typ)	Phase Unbalance(Typ)		DC Current	RF Power	Frequency
	Pri:Sec (6-4:1-3)	2000-3000 MHz	1000-2000 MHz	4.5-1000 MHz	4.5-2000MHz	4.5-1000 MHz	1000-2000 MHz	30mA	250mW	4.5-3000 MHz
RFT-134SG	1:1	3.0dB	2.0dB	1.0dB	0.5dB	2.0°	3.0°			

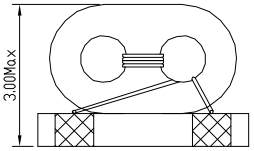
Note:Insertion Loss is referenced to mid-band loss,0.5dB typ.

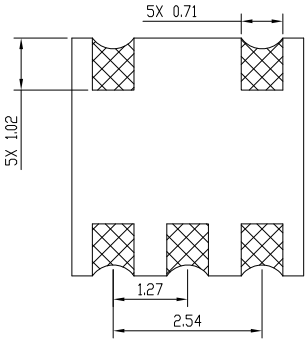
MECHANICAL DIMENSIONS(units:mm)





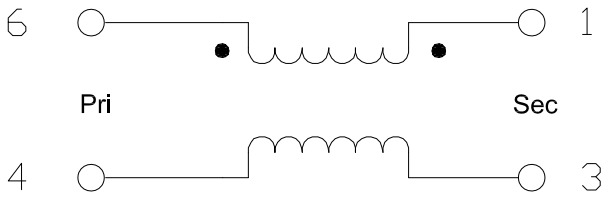
Recommended PAD Layout





Unless otherwise specified all tolerances are:±0.25 mm

SCHEMATIC



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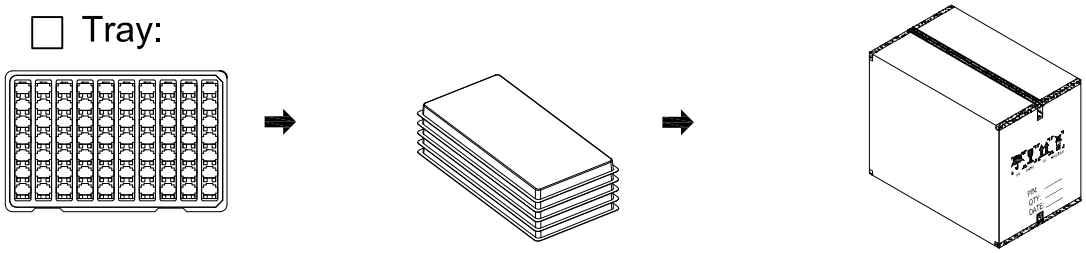
RoHS

PACKING:

☐ Tray:

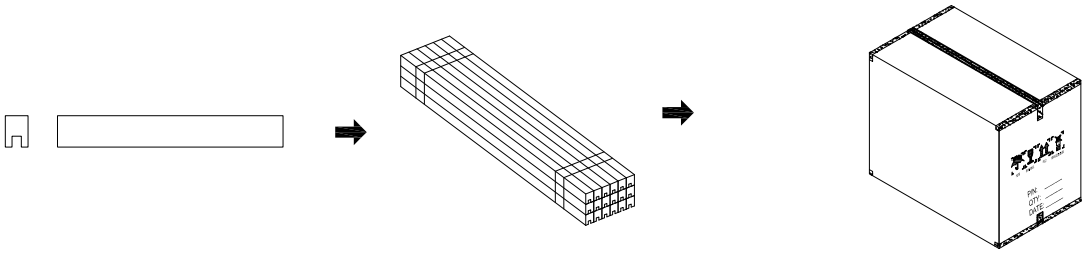


Q'ty

_____ PCS Per Tray

_____ PCS Per Carton

☐ Tube:

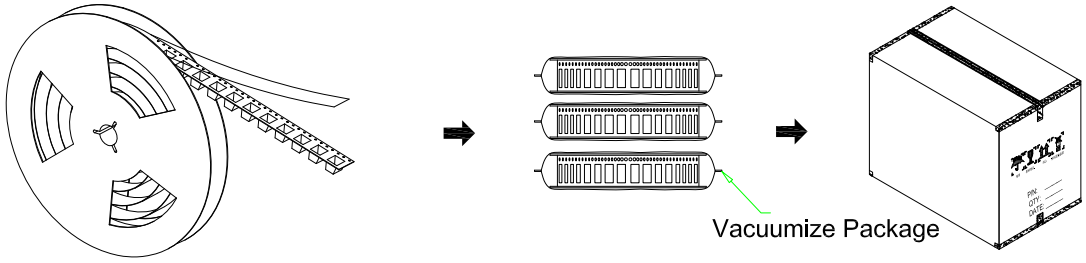


Q'ty

_____ PCS Per Tube

_____ PCS Per Carton

☑ Reel:



Q'ty

2500 PCS Per Reel

30000 PCS Per Carton

MOISTURE SENSITIVE LEVEL:

1. Level:1
2. Shelf Life:Unlimited
3. Storage Condition:<=30℃/85% RH

RECOMMENDED SOLDERING PROFILE:

☑ 1. Reflow soldering profile(According to IPC/JEDEC J-STD-020C)

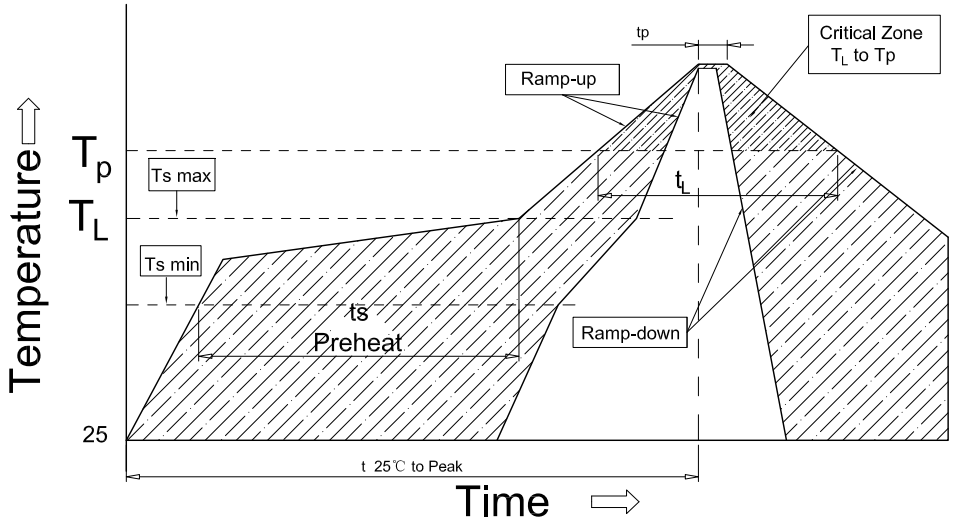


Table 1-1 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T_{Smax} to Tp)	3℃/second max	3℃/second max
Preheat -Temperature Min (T_{Smin}) -Temperature Max (T_{Smax}) -Time (t_{Smin} to t_{Smax})	100℃ 150℃ 60-120 seconds	150℃ 200℃ 60-180 seconds
Time maintained above: -Temperature (T_L) -Time (t_L)	183℃ 60-150 seconds	217℃ 60-150 seconds
Peak/Classification Temperature(T_p)	See IPC/JEDEC J-STD-020CTable 4-1	See IPC/JEDEC J-STD-020CTable 4-2
Time within 5℃ of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6℃/second max	6℃/second max
Time 25℃ to Peak Temperature	6 minutes max	8 minutes max

Note1:All temperatures refer to topside of the package, measured on the package body surface

- Suggested soldering process:Reflow soldering
  Solder Paste: Sn96.5Ag3.0Cu0.5
  Silkscreen thickness:0.15mm Min.

☐ 2. Wave soldering profile